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Contact: Amy McGrath, Communications Director
DfR Solutions
amcgrath@dfrsolutions.com
267-337-2495

DfR Solutions to Tackle Thermal Issues in Electronics at InterPACK

Presenting solutions to battery failure and thermal fatigue of BGAs

Beltsville, MD – June 15, 2018 – DfR Solutions, pioneer in Reliability Physics and leader in quality, reliability, and durability solutions for the electronics industry, today announced that it would be presenting two sessions at InterPACK, Packaging and Integration of Electronic and Photonic Microsystems August 27 and 28 in San Francisco. Dr. Vidyu Challa will present *How to Qualify Your Batteries to Prevent Failures and Thermal Events* on August 27 and participate in the Women in Engineering Panel on August 28. Maxim Serebreni will present the paper, *Experimental and Numerical Investigation of Underfill Materials on Thermal Cycle Fatigue of Second Level Solder Interconnects*.

The rising demand for Internet of Things and Machine to Machine applications makes reliable battery power an absolute necessity. In her presentation, Dr. Challa will address how designers can balance the need for power, size, cost, and time-to-market while avoiding catastrophic battery failure. Attendees will learn about the causes of battery failure, the role that cell design plays in safety and reliability, battery management systems, and how to qualify cell manufacturers.

In his presentation, Mr. Serebreni will demonstrate the impact underfill properties have on the durability of BGA solder joints under various thermal loading conditions using experimental and numerical results. Application of underfills in modern electronic assemblies are becoming a necessity to meet reliability requirements in harsh use environments. Proper selection of underfilling materials require understanding both the temperature dependent properties and thermal loading to which electronic components are subjected.

InterPACK is the premier international conference for the exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronics packaging and heterogeneous integration. It is the flagship conference of the American Society of Mechanical Engineers, Electronic and Photonic Packaging Division.

‘Electronics are getting hotter and more susceptible to failure,’ said Dr. Craig Hillman, CEO of DfR Solutions. ‘They are becoming smaller, more powerful, and are operating in harsher environments as in automotive and avionics applications,’ said Hillman. ‘At DfR Solutions, we are dedicated to preventing these failures through the use of Reliability Physics Analysis and other tools. We are

eager to have the opportunity to discuss these important issues at the InterPACK conference this year,' stated Hillman.

About DfR Solutions

DfR Solutions is world-renowned for its expertise in applying Reliability Physics Analysis to electronics technologies and is a leading provider of quality, reliability, and durability research and consulting to the electronics industry. The company pioneered the use of Reliability Physics with its innovative, Sherlock Automated Design Analysis™ software providing crucial insights and solutions early in product design and throughout the product life cycle. DfR Solutions empowers its customers to accelerate and maximize product development while saving time, managing resources, and improving customer satisfaction. The company supports Fortune 500 clients in every industry including aerospace/avionics, automotive, consumer, industrial, medical, military, solar and telecommunications. For more information about DfR Solutions, visit www.dfrsolutions.com.

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